innodisk

Total Solution For
Embedded Peripherals

EMPL-G102

mPCIe to Single Isolated GbE LAN Horizontal Module

Customer: _____

Customer Part Number: _____

Innodisk Part Number: _____

Innodisk Model Name: _____

Date: _____

Innodisk Approver	Customer Approver

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REVISION HISTORY

Revision	Description	Date
1.0	First Released	Sep , 2025

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1. Product Introduction

1.1. Overview

Innodisk EMPL-G102 is designed with standard Mini PCI Express form factor, with horizontal LAN connector. EMPL-G102 supports PCIe Gen 2.1 with a single lane to single isolated GbE LAN, optimized for higher performance and lower power, which brings you a flexible expansion solution for embedded systems.

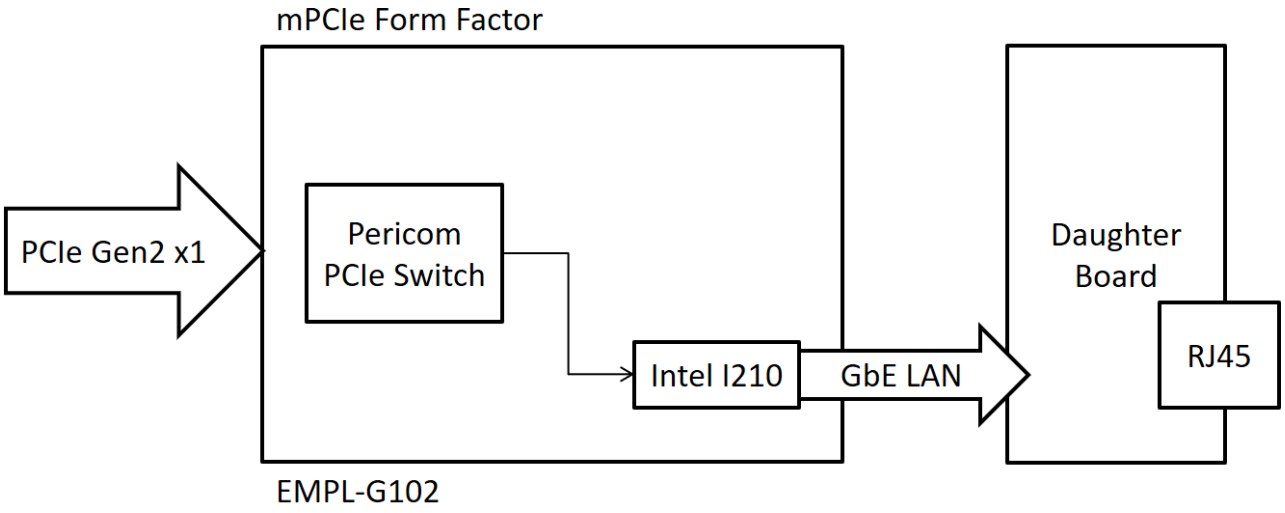


Figure 1: Block Diagram

1.2. Features

- Single isolated GbE LAN ports
- Complies with IEC 60950-1:2005 + A1: 2009 + A2:2013 2kV HiPOT protection
- Complies with EN61000-4-2 (ESD) Air-15kV, Contact-8kV
- Flexible daughter board with cable to fit into different system
- Optional terminal mounting hole or bracket for daughter board

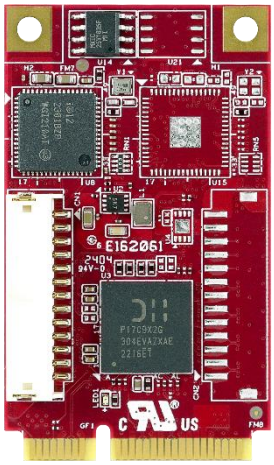


Figure 2: mPCIe Board Picture

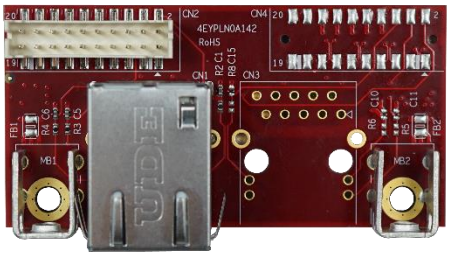


Figure 3: Mounting Hole Daughter Board Picture (EMPL-G102-C3/W3)

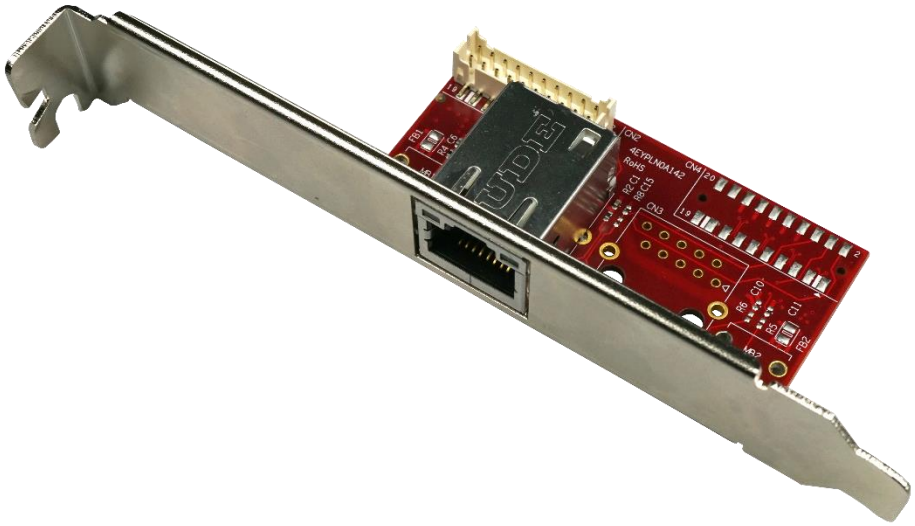


Figure 4: Bracket Daughter Board Picture (EMPL-G102-C4/W4)

2. Product Specifications

2.1. Device Parameters

Table 1: Device Parameters

Form Factor	mPCIe
Input I/F	PCI Express 2.1 x 1
Output I/F	GbE LAN x 1
Output Connector	RJ45 x 1
Dimension (WxLxH)	mPCIe Board: 30 x 50.9 x 5.8 mm Daughter Board: 30 x 59.95 x 19.69 mm

2.2. Electrical Specifications

2.2.1. Power Requirement

Table 2: Power Requirement

Item	Connector	Rating
Input voltage	mPCIe Golden Finger	+3.3 DC +-5%

2.2.2. Power Consumption

Table 3: Power Consumption

Full Load (mA)	Voltage (V)
200	3.3

2.3. Environmental Specifications

2.3.1. Temperature Ranges

Table 4: Temperature Ranges

Temperature	Range
Operating	Standard Grade: 0°C to +70°C Industrial Grade: -40°C to +85°
Storage	-55°C to +95°

2.3.2. Humidity

Relative Humidity: 10-95%, non-condensing

2.3.3. Shock and Vibration

Table 5: Shock and Vibration

Reliability	Test Conditions	Reference Standards
Vibration	7 Hz to 2K Hz, 20G, 3 axes	IEC 68-2-6
Mechanical Shock	Duration: 0.5ms, 1500 G, 3 axes	IEC 68-2-27

2.3.4. Mean Time between Failure (MTBF)

Reliability prediction methodology provides the basis for reliability evaluation and analysis. The purpose of the prediction is to predict the life time of the product in units of failure rate and MTBF.

Table 6: Mean Time between Failure (MTBF)

Product	Condition	MTBF (Hours)
EMPL-G102-C3/W3	The analysis is at 25°C ambient temperature by Telcordia SR-332, Issues 4, Method I, Case 3 under Ground Benign, Controlled environment, 50% operation stress	20,086,554
EMPL-G102-C4/W4	The analysis is at 25°C ambient temperature by Telcordia SR-332, Issues 4, Method I, Case 3 under Ground Benign, Controlled environment, 50% operation stress	22,098,972

2.4. CE and FCC Compatibility

EMPL-G102 conforms to CE and FCC requirements.

2.5. RoHS Compliance

EMPL-G102 is fully compliant with RoHS directive.

2.6. Hardware

2.6.1. Layout

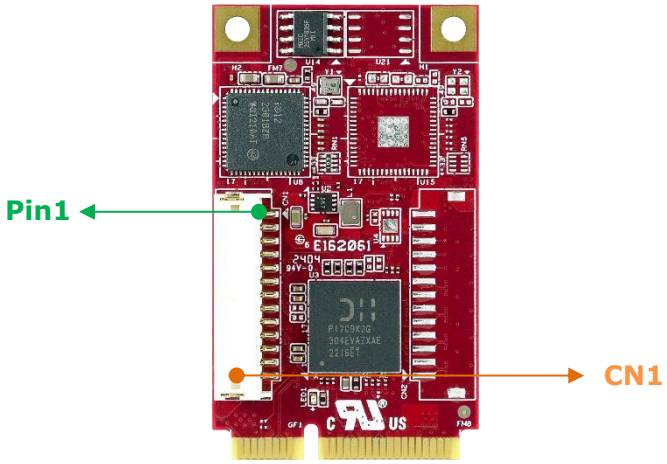


Table 7: mPCIe PCB Layout Legend

Label	Connector Type	Function
CN1	Wire to board SMD 2*10P 180° P:2.00mm H:4.0mm	GbE LAN Signal 10/100/1000 LED Signal

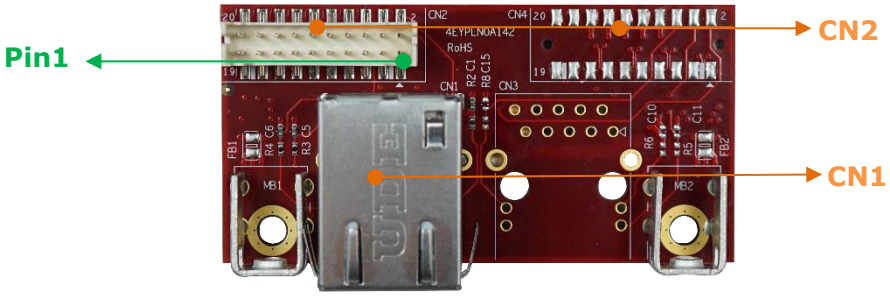


Table 8: Daughter Board PCB Layout Legend

Label	Connector Type	Function
CN1	10/100/1000 Base-T RJ45 DIP 10P8C 90° LED: Green-Orange/Green	GbE LAN Port 10/100/1000 LED Indicator
CN2	Wire to board SMD 2*10P 180° P:2.00mm H:4.0mm	GbE LAN Signal 10/100/1000 LED Signal

2.6.2. Pin Define

Table 9: mPCIe Pin Define

Signal Name	Pin #	Pin #	Signal Name
NC	**51**	**52**	3.3V AUX
NC	**49**	**50**	GND
NC	**47**	**48**	NC
NC	**45**	**46**	NC
GND	**43**	**44**	NC
3.3V AUX	**41**	**42**	NC
3.3V AUX	**39**	**40**	GND
GND	**37**	**38**	NC
GND	**35**	**36**	NC
RX+	**33**	**34**	GND
RX-	**31**	**32**	SMBDATA
GND	**29**	**30**	SMBCLK
GND	**27**	**28**	NC
TX+	**25**	**26**	GND
TX-	**23**	**24**	3.3V AUX
GND	**21**	**22**	PERST#
NC	**19**	**20**	NC
NC	**17**	**18**	GND
GND	**15**	**16**	NC
CLK+	**13**	**14**	NC
CLK-	**11**	**12**	NC
GND	**9**	**10**	NC
GND	**7**	**8**	NC
NC	**5**	**6**	NC
NC	**3**	**4**	GND
PE_WAKE_N	**1**	**2**	3.3V AUX

2.6.3. I/O Connector Mechanical Drawing & Pin Defines

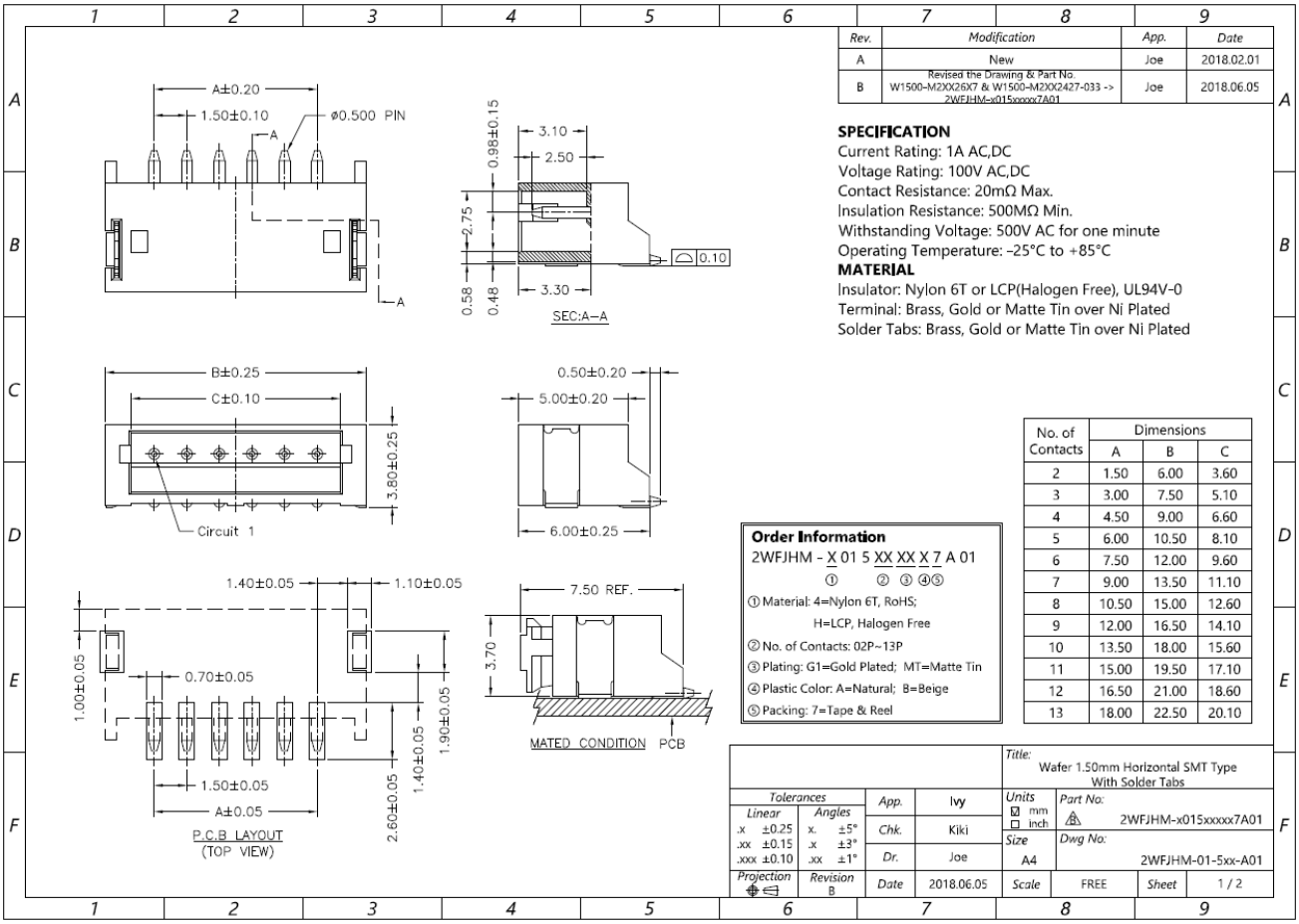


Figure 5: Wire to Board SMD 2*10P Connector Drawing

Table 10: Wire to Board SMD 2*10P Connector Pin Define

Signal Name	Pin #	Pin #	Signal Name
LINK_100_N	**2**	**1**	MDI0P_IC
LINK_ACT_N	**4**	**3**	MDI0N_IC
LINK_1000_N	**6**	**5**	MDI1P_IC
GND	**8**	**7**	MDI1N_IC
GND	**10**	**9**	MDI2P_IC
GND	**12**	**11**	MDI2N_IC
3.3V	**14**	**13**	MDI3P_IC
3.3V	**16**	**15**	MDI3N_IC
NC	**18**	**17**	NC
NC	**20**	**19**	NC

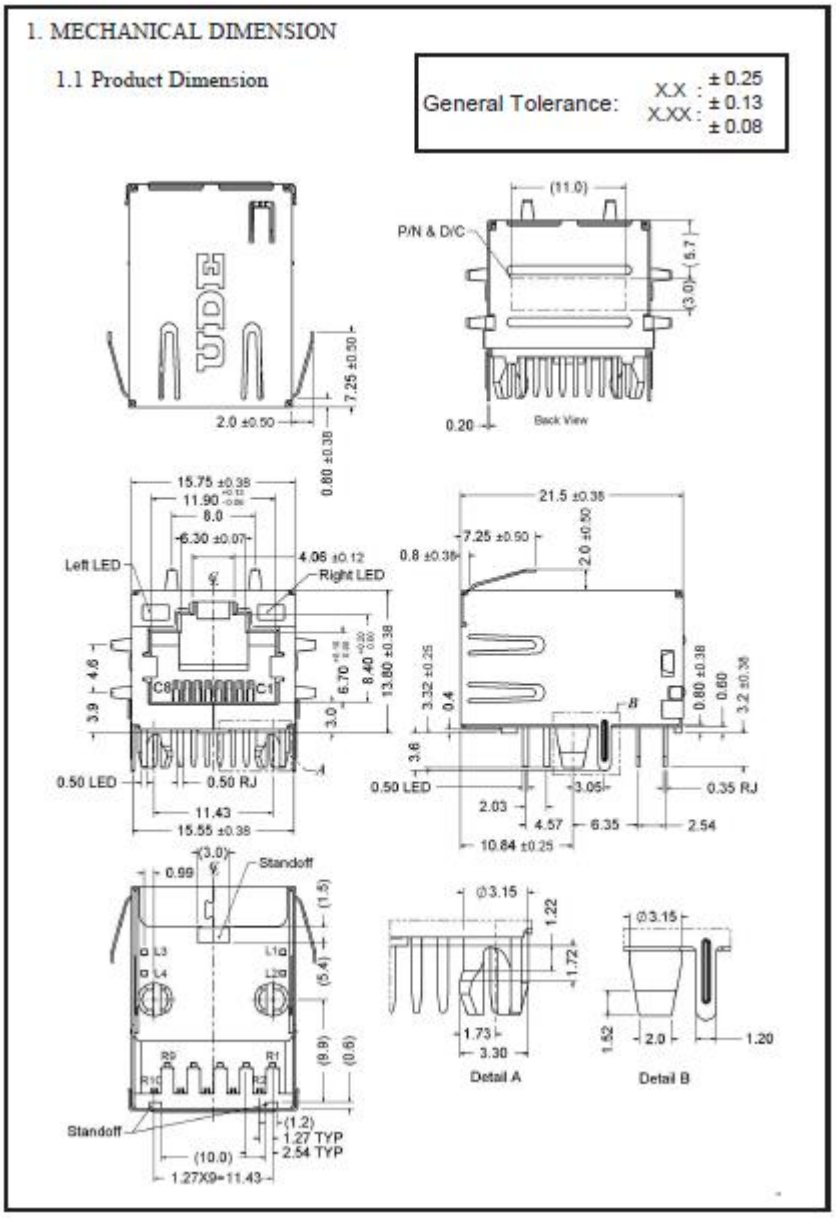
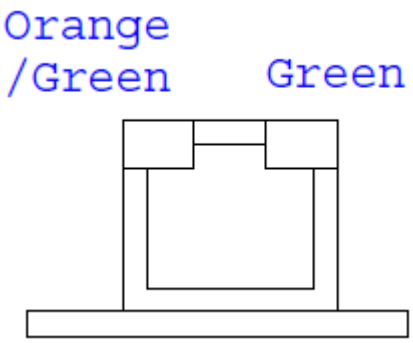


Figure 6: RJ45 Connector Drawing

Table 11: RJ45 LAN LED Table



Speed	Orange/Green (Status)	Green (Active/Link)
10M	OFF	Flash
100M	ON (Green)	Flash
1G	ON (Orange)	Flash

2.6.4. EMPL-G102 Mechanical Drawing

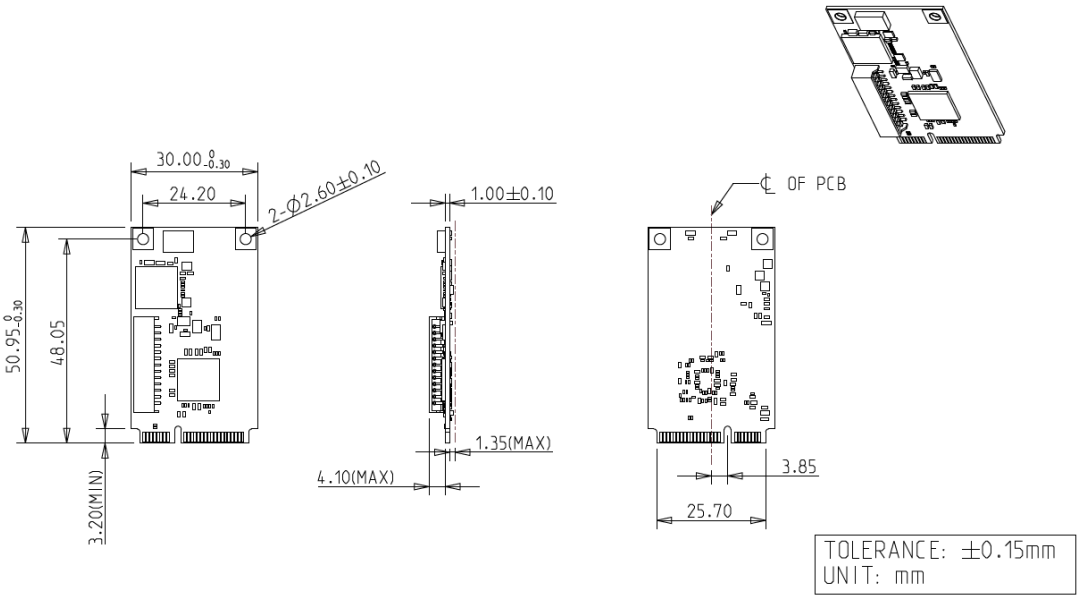


Figure 7: EMPL-G102 mPCIe Board Drawing

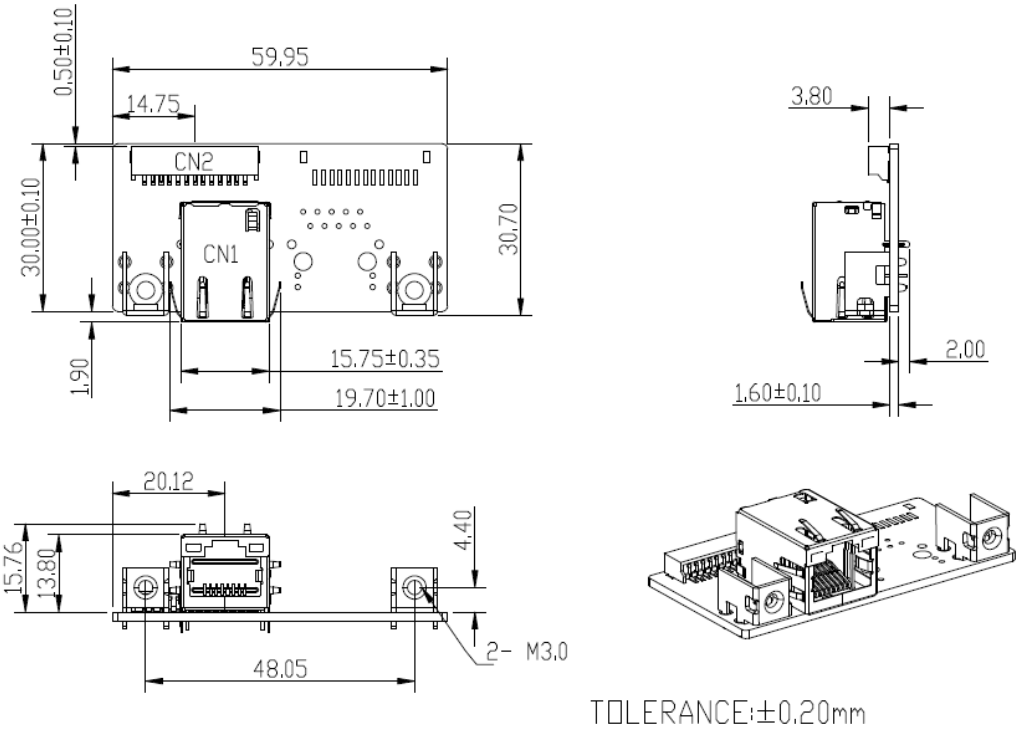


Figure 8: Mounting Hole Daughter Board Drawing (EMPL-G102-C3/W3)

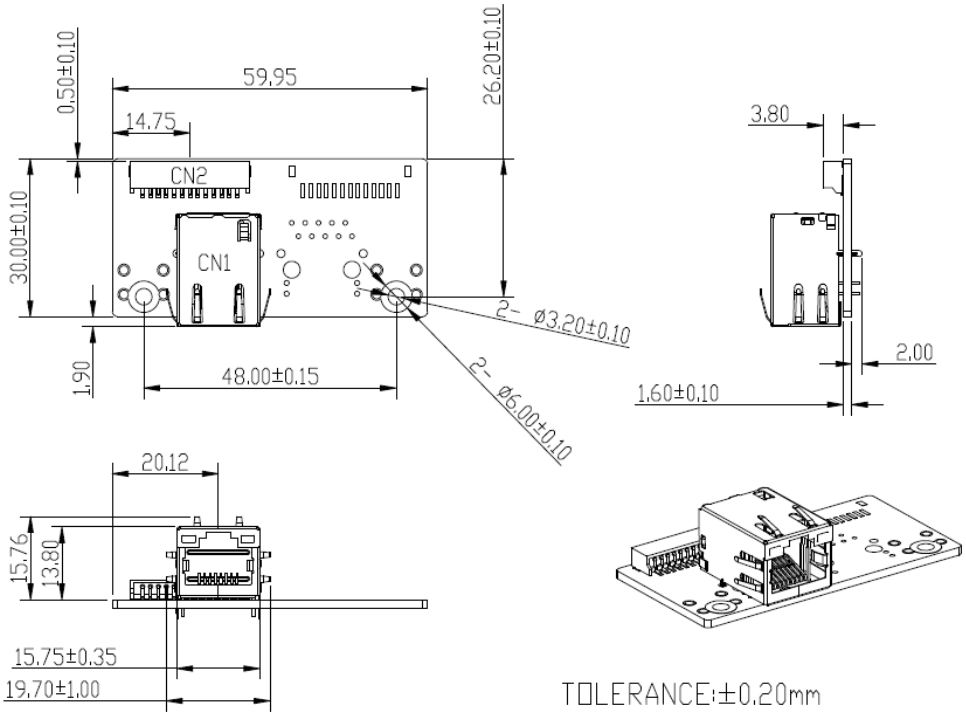


Figure 9: Bracket Daughter Board Drawing (EMPL-G102-C4/W4)

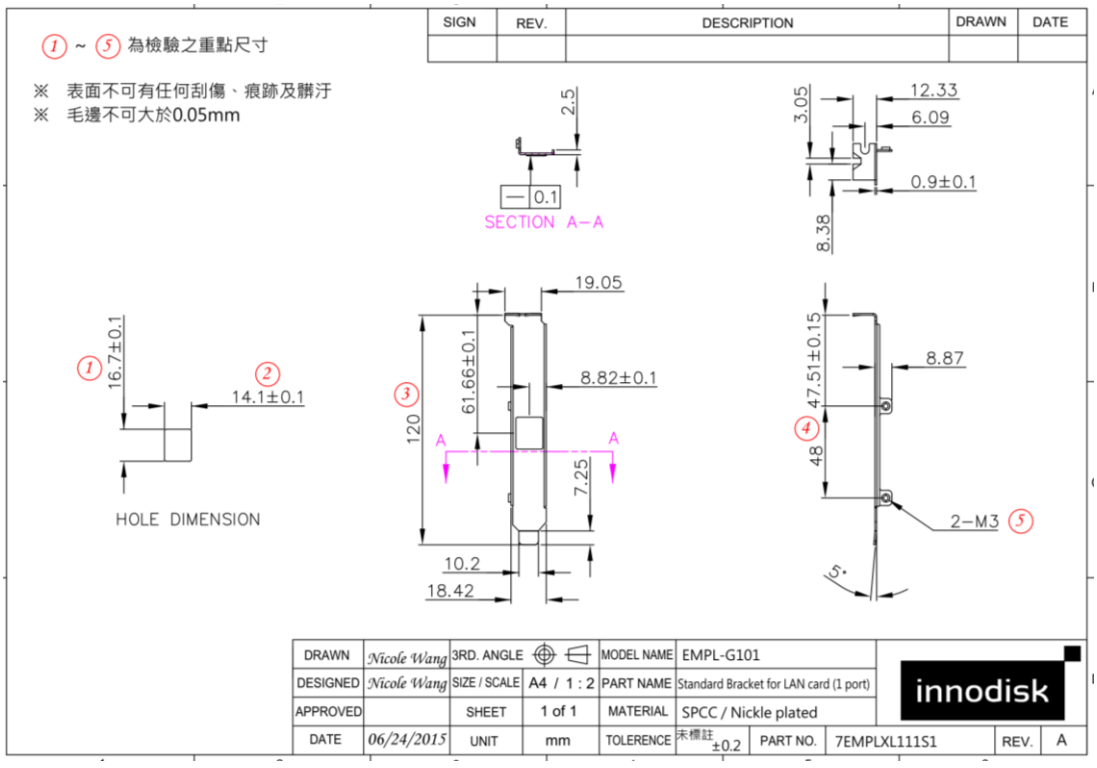


Figure 10: Bracket Drawing

2.6.5. Cable Mechanical Drawing

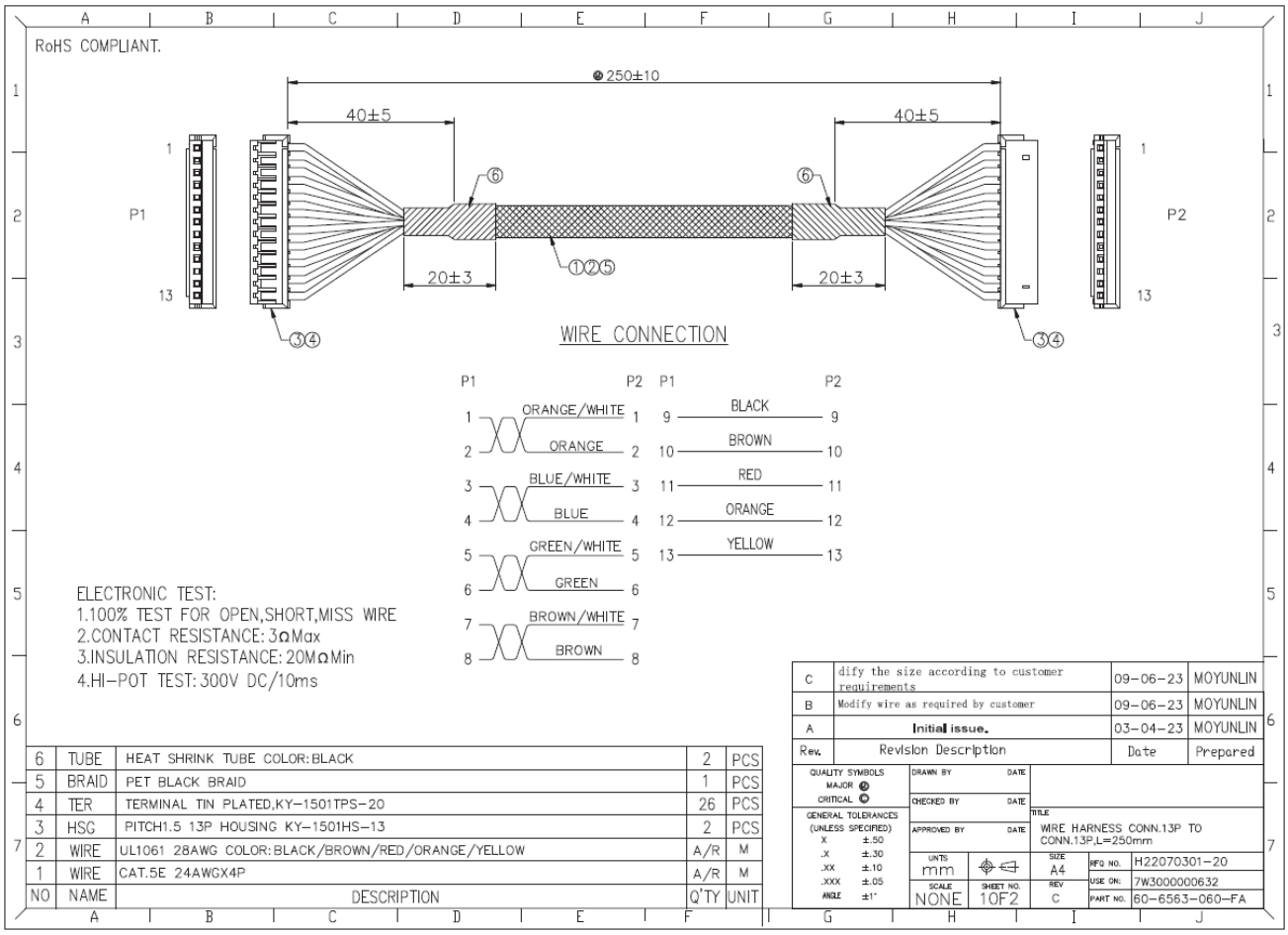


Figure 11: Board to Board LAN Cable Drawing

2.6.6. Packing List

- EMPL-G102 mPCIe Board x 1
- EMPL-G102 Daughter Board x 1
- Board to Board LAN Cable x 1
- Bracket x 1 (EMPL-G102-C4/W4 only)
- Screw M3*5 Silver x 2 (EMPL-G102 C4/W4 only)

2.7. Software Support

- Windows: XP(32bit), 7(32/64bit), 8/8.1(32/64 bit), 10(32/64bit), and later versions.
- Linux: Kernel 2.4 above.

3. Installation Guide

Please download driver from Myinnodisk web site.
https://myinnodisk.innodisk.com/myinnodisk/Login.aspx

Or you can download intel i210 chip driver from intel official web site directly.
https://downloadcenter.intel.com/product/64399/Intel-Ethernet-Controller-I210-Series

4. Appedix

宜鼎國際股份有限公司
Innodisk Corporation
REACH Declaration

Tel:(02)7703-3000 Fax:(02) 7703-3555 Internet: https://www.innodisk.com/

Innodisk Corporation pursues its social responsibility for global environmental preservation by committing to be compliant with REACH regulation (REGULATION (EC) No 1907/2006).
We hereby confirm that the product(s),
Scope: Flash Memory, DRAM module and Embedded peripherals products.

■ The standard products of not listed in the ***Appendix2*** meet the requirements of REACH SVHC regulations(SVHCs < 0.1% in Article), as described in the candidate list table currently including 211 substances and shown on the ECHA website. (http://echa.europa.eu/de/candidate-list-table).

■ Contain(s) one or more hazardous substances or constituents exceeding 0.1 % by weight in article if not otherwise specified in candidate list table.
Where the threshold value is exceeded, the substances in question are to be declared in accompanying. (SVHCs > 0.1% in Article).

■ Comply with REACH Annex XVII.

Guarantor

Company name 公司名稱： Innodisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人：Yichuan Chen 陳怡全

Company Representative Title 公司代表人職稱： QA Manager 品保經理

Date 日期： 2021 / 03 / 03

innodisk

宜鼎國際股份有限公司
Innodisk Corporation

Tel:(02)7703-3000 Internet: https://www.innodisk.com/

RoHS 自我宣告書(RoHS Declaration of Conformity)

Manufacturer Products: All Innodisk EM FLASH, DRAM and EP products

一、 宜鼎國際股份有限公司（以下稱本公司）特此保證售予貴公司之所有產品，皆符合歐盟 2011/65/EU 及(EU) 2015/863 關於 RoHS 之規範要求。
Innodisk Corporation declares that all products sold to the company, are complied with European Union RoHS Directive (2011/65/EU) and (EU) 2015/863 requirement.

二、 本公司同意因本保證書或與本保證書相關事宜有所爭議時，雙方宜友好協商，達成協議。
Innodisk Corporation agrees that both parties shall settle any dispute arising from or in connection with this Declaration of Conformity by friendly negotiations.

三、 本公司聲明我們的產品符合 RoHS 指令的附件中(7a)、(7c-I)允許豁免。
We declare, our products permitted by the following exemptions specified in the Annex of the RoHS directive.
※ (7a) Lead in high melting temperature type solders(i.e. lead-based alloys containing 85% by weight or more lead).
※ (7C-I) Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound.

Name of hazardous substance	Limited of RoHS ppm (mg/kg)
鉛 (Pb)	< 1000 ppm
汞 (Hg)	< 1000 ppm
鎘 (Cd)	< 100 ppm
六價鉻 (Cr 6+)	< 1000 ppm
多溴聯苯 (PBBs)	< 1000 ppm
多溴二苯醚 (PBDEs)	< 1000 ppm
鄰苯二甲酸二(2-乙基己基)酯 (DEHP)	< 1000 ppm
鄰苯二甲酸丁酯苯甲酯 (BBP)	< 1000 ppm
鄰苯二甲酸二丁酯 (DBP)	< 1000 ppm
鄰苯二甲酸二異丁酯 (DIBP)	< 1000 ppm

立 保 證 書 人 (Guarantor)

Company name 公司名稱： Innodisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人： Randy Chien 簡川勝

Company Representative Title 公司代表人職稱： Chairman 董事長

Date 日期： 2020 / 03 / 03

Certificate

Issue Date: January 16, 2015
Ref. Report No. ISL-15LE019CE

Product Name	:	LAN Module
Model(s)	:	E%PL-G*01-*1 (% : form factor (2: 2.5" SSD, 3. DDR3 DIMM, D: Dongle, G: NGFF, M.2, H: mPCIe Half, L: PCIe Low profile, M: mPCIe, S: PCIe Standard, X: Multi, Z: Others) * : Series (1~9, A~Z))
Responsible Party	:	Innodisk Corporation
Address	:	5F.No.237, Sec. 1, Datong Rd., Xizhi Dist., New Taipei City 221, Taiwan (R.O.C.)

We, **International Standards Laboratory**, hereby certify that:

The device bearing the trade name and model specified above has been shown to comply with the applicable technical standards as indicated in the measurement report and was tested in accordance with the measurement procedures specified in European Council Directive- EMC Directive 2004/108/EC. The device was passed the test performed according to :

CE

Standards:

EN 55022: 2010+AC2011 and CISPR 22: 2008 (modified)
EN 61000-3-2: 2006+A1:2009 +A2:2009 and IEC 61000-3-2: 2005+A1:2008 +A2:2009
EN 61000-3-3: 2013 and IEC 61000-3-3: 2013
EN 55024: 2010 and CISPR 24: 2010
EN 61000-4-2: 2009 and IEC 61000-4-2: 2008
EN 61000-4-3: 2006+A1: 2008 +A2: 2010 and
IEC 61000-4-3:2006+A1: 2007+A2: 2010
EN 61000-4-4:2012 and IEC 61000-4-4:2012

I attest to the accuracy of data and all measurements reported herein were performed by me or were made under my supervision and are correct to the best of my knowledge and belief. I assume full responsibility for the completeness of these measurements and vouch for the qualifications of all persons taking them.

International Standards Laboratory

Jim Chu / Director

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Nemko ELA113A

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Tel: 886-3-407-1718; Fax: 886-3407-1738

Nemko ELA113B

Certificate

Issue Date: January 16, 2015
Ref. Report No. ISL-15LE019FB

Product Name	:	LAN Module
Model(s)	:	E%PL-G*01-*1 (% : form factor (2: 2.5" SSD, 3. DDR3 DIMM, D: Dongle, G: NGFF, M.2, H: mPCIe Half, L: PCIe Low profile, M: mPCIe, S: PCIe Standard, X: Multi, Z: Others) * : Series (1~9, A~Z))
Applicant	:	Innodisk Corporation
Address	:	5F.No.237, Sec. 1, Datong Rd., Xizhi Dist., New Taipei City 221, Taiwan (R.O.C.)

We, International Standards Laboratory, hereby certify that:

The device bearing the trade name and model specified above has been shown to comply with the applicable technical standards as indicated in the measurement report and was tested in accordance with the measurement procedures specified. (refer to Test Report if any modifications were made for compliance).

Standards:

FCC CFR Title 47 Part 15 Subpart B: 2012- Section 15.107 and 15.109
ANSI C63.4-2009
Industry Canada Interference-Causing Equipment Standard ICES-003 Issue 5: 2012

Class B

I attest to the accuracy of data and all measurements reported herein were performed by me or were made under my supervision and are correct to the best of my knowledge and belief. I assume full responsibility for the completeness of these measurements and vouch for the qualifications of all persons taking them.

International Standards Laboratory

Jim Chu / Director

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September 12, 2025